

**5.8A, 30V, 0.037 Ohm, Dual N-Channel, Logic Level Power MOSFET**

This power MOSFET is manufactured using an innovative process. This advanced process technology achieves the lowest possible on-resistance per silicon area, resulting in outstanding performance. This device is capable of withstanding high energy in the avalanche mode and the diode exhibits very low reverse recovery time and stored charge. It was designed for use in applications where power efficiency is important, such as switching regulators, switching converters, motor drivers, relay drivers, low-voltage bus switches, and power management in portable and battery-operated products.

**Ordering Information**

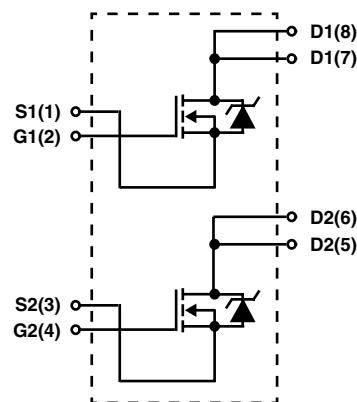
PART NUMBER	PACKAGE	BRAND
HP4936DY	SO-8	P4936DY

NOTE: When ordering, use the entire part number. Add the suffix T to obtain the variant in tape and reel, e.g., HP4936DYT.

**Features**

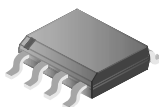
- Logic Level Gate Drive
- 5.8A, 30V
- $r_{DS(ON)} = 0.037\Omega$  at  $I_D = 5.8A, V_{GS} = 10V$
- $r_{DS(ON)} = 0.055\Omega$  at  $I_D = 4.7A, V_{GS} = 4.5V$
- Related Literature
  - TB334, "Guidelines for Soldering Surface Mount Components to PC Boards"

**Symbol**



**Packaging**

SO-8



# HP4936DY

## Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ , Unless Otherwise Specified

	HP4936DY	UNITS
Drain to Source Voltage (Note 1) . . . . .	$V_{DSS}$	30 V
Drain to Gate Voltage ( $R_{GS} = 20k\Omega$ ) (Note 1) . . . . .	$V_{DGR}$	30 V
Gate to Source Voltage . . . . .	$V_{GS}$	$\pm 16$ V
Drain Current		
Continuous . . . . .	$I_D$	5.8 A
Pulsed Drain Current (10 $\mu$ s Pulse Width) . . . . .	$I_{DM}$	30 A
Power Dissipation . . . . .	$P_D$	2 W
Derate Above $25^\circ\text{C}$ . . . . .		0.02 W/ $^\circ\text{C}$
Operating and Storage Temperature . . . . .	$T_J, T_{STG}$	-55 to 150 $^\circ\text{C}$
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10s. . . . .	$T_L$	300 $^\circ\text{C}$
Package Body for 10s, See Techbrief 334 . . . . .	$T_{pkg}$	260 $^\circ\text{C}$

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### NOTE:

- $T_A = 25^\circ\text{C}$  to  $125^\circ\text{C}$ .

## Electrical Specifications $T_A = 25^\circ\text{C}$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	$BV_{DSS}$	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	30	-	-	V
Gate to Source Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$ (Figure 9)	1	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}, T_A = 55^\circ\text{C}$	-	-	25	$\mu\text{A}$
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 16\text{V}$	-	-	100	nA
Drain to Source On Resistance	$r_{DS(ON)}$	$I_D = 4.7\text{A}, V_{GS} = 4.5\text{V}$ (Figures 6, 8)	-	0.042	0.055	$\Omega$
		$I_D = 5.8\text{A}, V_{GS} = 10\text{V}$ (Figures 6, 8)	-	0.030	0.037	$\Omega$
Turn-On Delay Time	$t_{d(ON)}$	$V_{DD} = 15\text{V}, I_D \cong 1\text{A},$ $R_L = 15\Omega, V_{GEN} = 10\text{V},$ $R_{GS} = 6\Omega$ (Figures 12, 13)	-	10	16	ns
Rise Time	$t_r$		-	10	16	ns
Turn-Off Delay Time	$t_{d(OFF)}$		-	27	40	ns
Fall Time	$t_f$		-	24	35	ns
Total Gate Charge	$Q_g$	$V_{DS} = 15\text{V}, V_{GS} = 10\text{V}, I_D \cong 5.8\text{A}$ (Figures 14, 15)	-	18	25	nC
Gate to Source Charge	$Q_{gs}$		-	4.5	-	nC
Gate to Drain Charge	$Q_{gd}$		-	2.5	-	nC
Input Capacitance	$C_{ISS}$	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V},$ $f = 1\text{MHz}$ (Figure 4)	-	625	-	pF
Output Capacitance	$C_{OSS}$		-	270	-	pF
Reverse Transfer Capacitance	$C_{RSS}$		-	50	-	pF
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	Pulse Width <10s (Figure 11) Device Mounted on FR-4 Material	-	-	62.5	$^\circ\text{C/W}$

## Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	$V_{SD}$	$I_{SD} = 1.7\text{A}$ (Figure 7)	-	0.8	1.2	V
Reverse Recovery Time	$t_{rr}$	$I_{SD} = 1.7\text{A}, dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	45	80	ns

Typical Performance Curves Unless Otherwise Specified

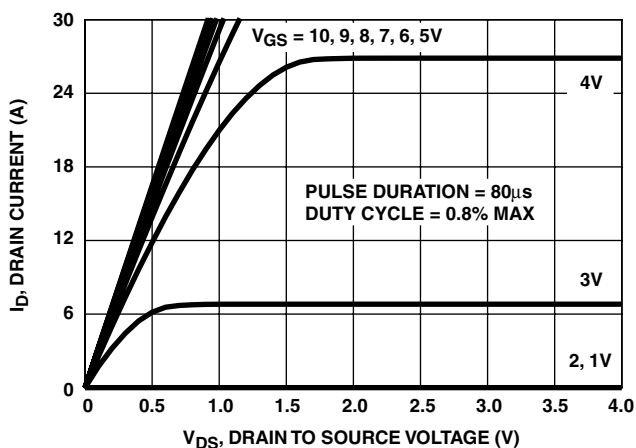


FIGURE 1. OUTPUT CHARACTERISTICS

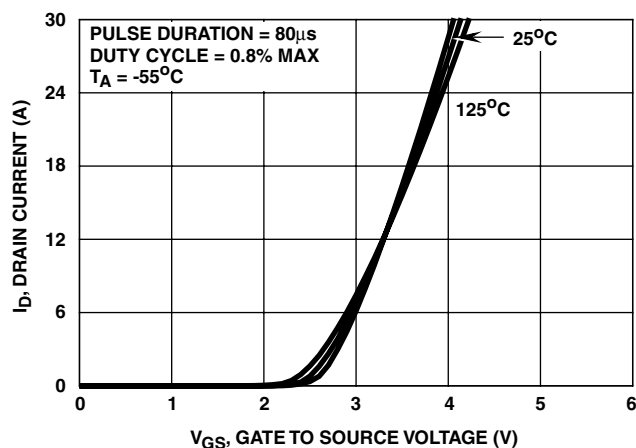


FIGURE 2. TRANSFER CHARACTERISTICS

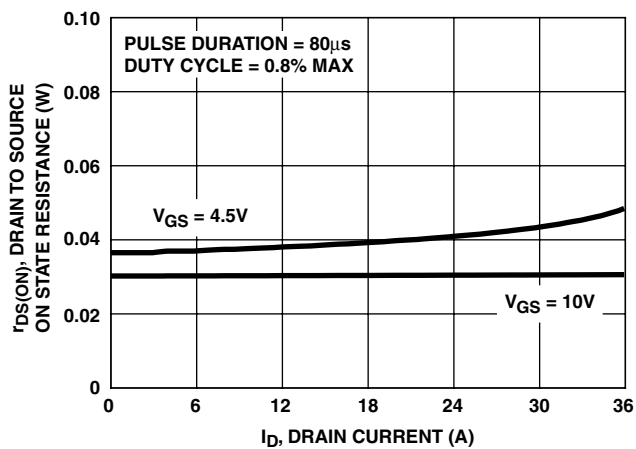


FIGURE 3. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

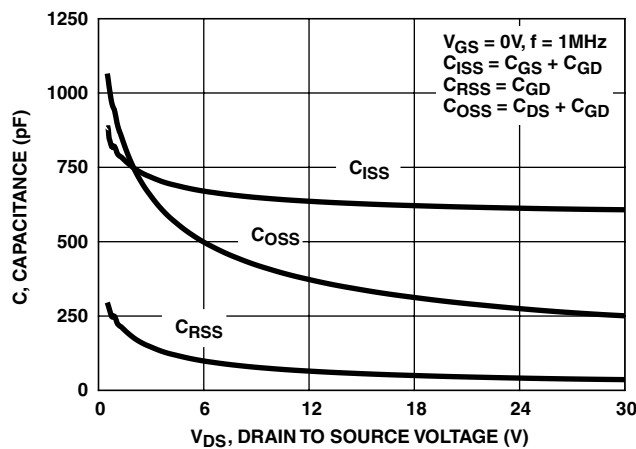


FIGURE 4. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

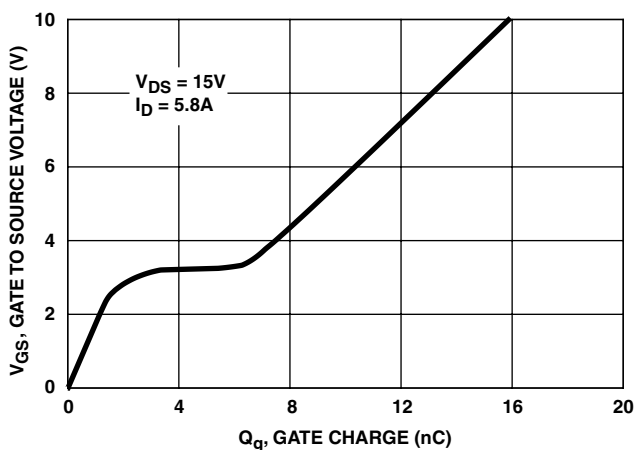


FIGURE 5. GATE TO SOURCE VOLTAGE vs GATE CHARGE

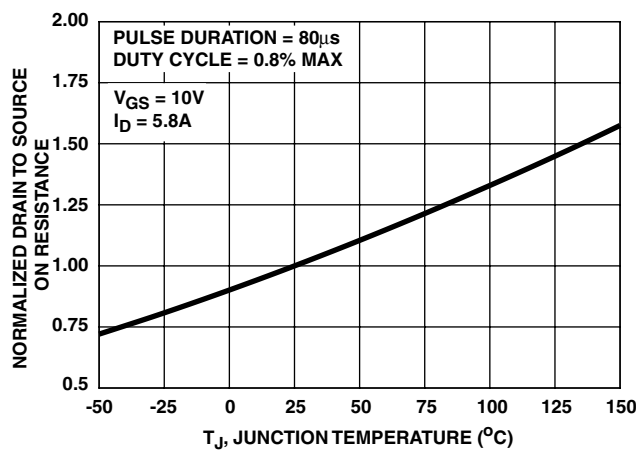


FIGURE 6. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

Typical Performance Curves Unless Otherwise Specified (Continued)

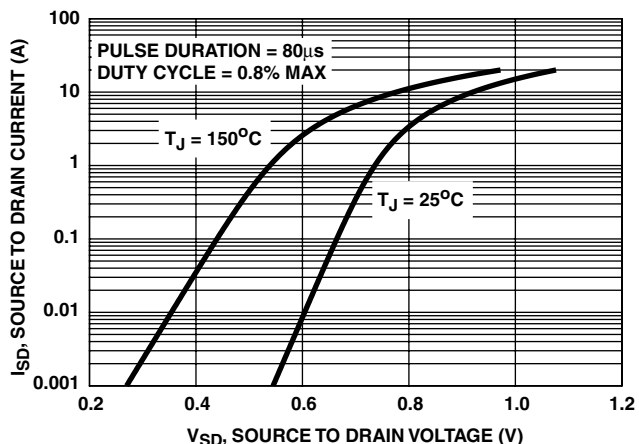


FIGURE 7. SOURCE TO DRAIN DIODE VOLTAGE

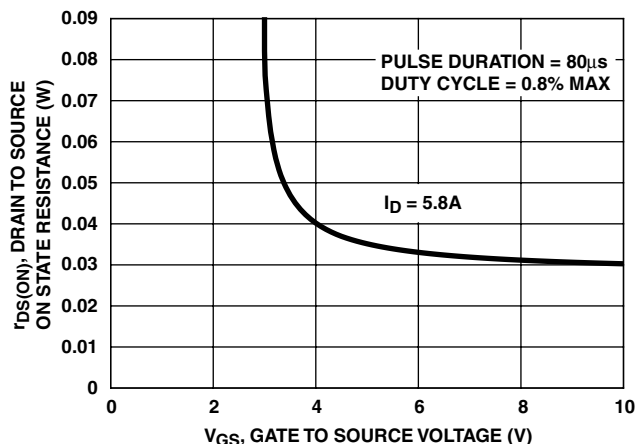


FIGURE 8. DRAIN TO SOURCE ON RESISTANCE vs GATE TO SOURCE VOLTAGE

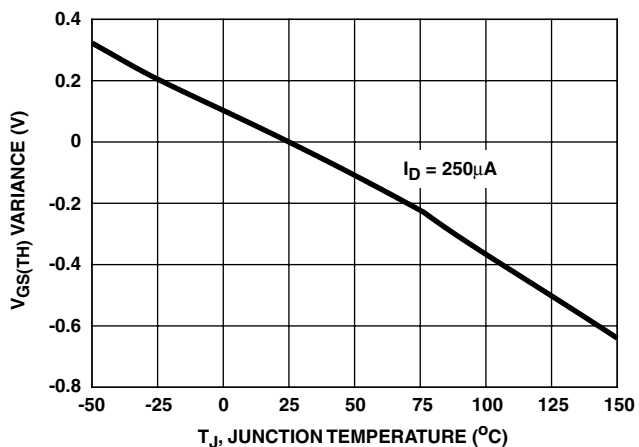


FIGURE 9. GATE THRESHOLD VOLTAGE VARIANCE vs JUNCTION TEMPERATURE

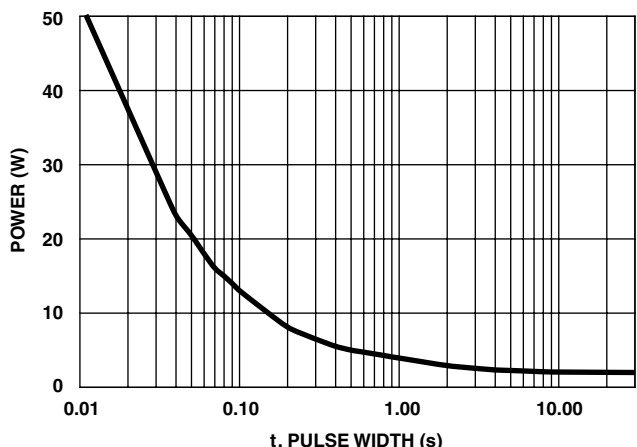


FIGURE 10. SINGLE PULSE POWER CAPABILITY vs PULSE WIDTH

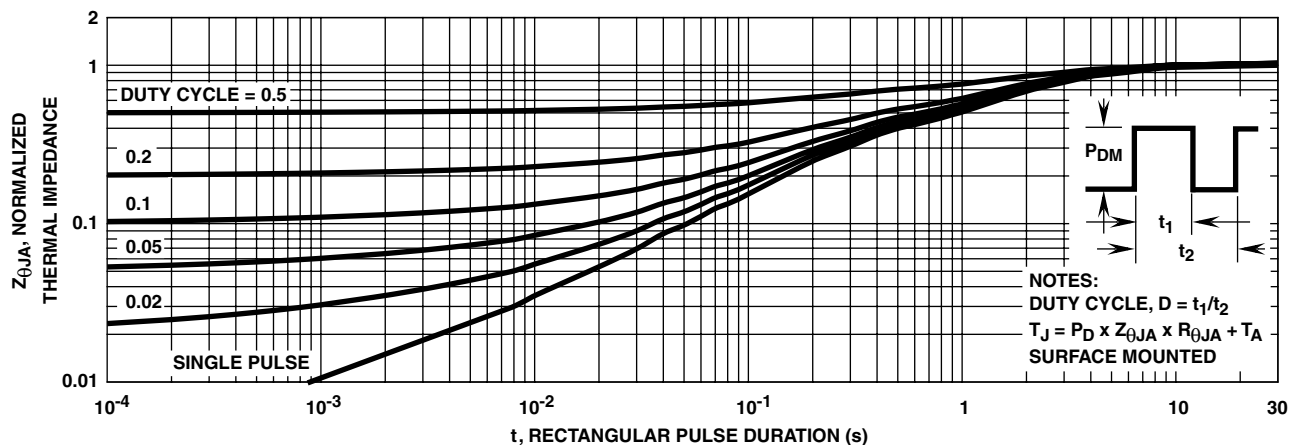


FIGURE 11. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE



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